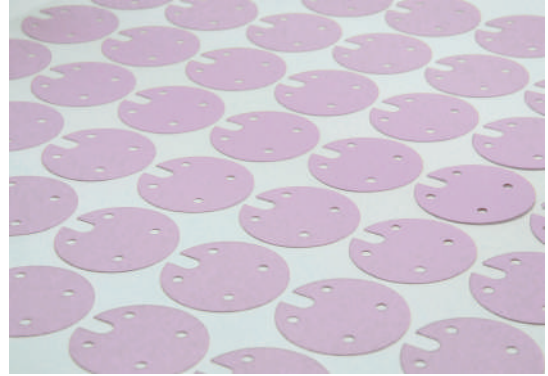


# T-top 800

## Ultra Soft & High Thermal Conductivity Pad

### Ultra Soft & High Thermal Conductivity interface materials.

LiPOLY T-top 800 is a highly conformable & ultra soft for low stress applications , high thermally conductive , non-flammable interface materials. It is excellent for filling small air gaps , making reliable contact with heat source & sink.



### Applications-

- Between CPU and heat sink.
- Between a component and heat sink.
- Flat-panel displays
- Power supplies
- High speed mass storage drives
- Telecommunication hardware

### Construction-

Series	Characteristics	Configurations
<b>T-top800</b>	Silicone compound with weak sticky surfaces.	Sheets form, Die-cuts parts

### Typical Properties-

Property		TESTMETHOD	UNIT
Color	Purple	Visual	-
Surface tack 2-side/1-side	2-side weak	-	-
Thickness	0.5~3.0	ASTM D374	mm
Density	3.3	ASTM D792	g/cm <sup>3</sup>
Application temperature	-60~150	-	°C
COMPRESSION			
Deflection @10 psi	3	-	%
Deflection @20 psi	15	-	%
Deflection @30 psi	33	-	%

※These data are provided for reference only. Engineers are reminded to test the material in varied application.

Deflection @40 psi	47	-	%
Deflection @50 psi	60	-	%
<b>ELECTRICA</b>			
Dielectric breakdown	10	ASTM D149	KV/mm
Surface resistivity	>10 <sup>11</sup>	ASTM D257	Ohm
Volume resistivity	>10 <sup>10</sup>	ASTM D257	Ohm-m
<b>THERMAL</b>			
Thermal Conductivity	8	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.295	ASTM D5470	°C-in <sup>2</sup> /W
Thermal impedance@20 psi	0.251	ASTM D5470	°C-in <sup>2</sup> /W
Thermal impedance@30 psi	0.213	ASTM D5470	°C-in <sup>2</sup> /W
Thermal impedance@40 psi	0.165	ASTM D5470	°C-in <sup>2</sup> /W
Thermal impedance@50 psi	0.134	ASTM D5470	°C-in <sup>2</sup> /W
<b>FLAME RATING</b>			
UL Flammability class	V-0	UL94	-